

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2935886

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	HAMZA YILMAZ	01/25/2013
	MADHUR BOBDE	01/25/2013
	HONG CHANG	01/25/2013
	YEEHENG LEE	01/25/2013
	DANIEL CALAFUT	01/25/2013
	JONGOH KIM	01/07/2013
	SIK LUI	01/25/2013
	JOHN CHEN	01/25/2013
RECEIVING PARTY DATA		
Name:	ALPHA AND OMEGA SEMICONDUCTOR INCORPORATED	
Street Address:	475 OAKMEAD PKWY	
City:	SUNNYVALE	
State/Country:	CALIFORNIA	
Postal Code:	94085	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14329806
CORRESPONDENCE DATA		
Fax Number:	(510)668-0239	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	510-668-0965	
Email:	stephen@jdipatent.com	
Correspondent Name:	JOSHUA D. ISENBERG JDI PATENT	
Address Line 1:	809 CORPORATE WAY	
Address Line 4:	FREMONT, CALIFORNIA 94539	
ATTORNEY DOCKET NUMBER:	ANO-58/DIV	
NAME OF SUBMITTER:	JOSHUA D. ISENBERG	
SIGNATURE:	/Joshua D. Isenberg, REg. No. 41088/	
DATE SIGNED:	07/11/2014	

PATENT

Total Attachments: 8

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ASSIGNMENT

**INVENTOR
AND CITY**

Whereas, I, **HAMZA YILMAZ** residing at
Saratoga, California, USA

have invented:

TITLE:

**DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY
MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS**

**DATE INVENTOR
SIGNED THE
DECLARATION**

and executed a United States patent application therefor

on _____, 2013. Said assignor hereby authorize and request
their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont,
California, to insert here in parentheses (Application number
14/329,806, filed July 11, 2014) the filing
date and application number of said application when known.

Whereas, **Alpha and Omega Semiconductor Incorporated**, a
California Corporation, having its registered address at 475 Oakmead
Pkwy, Sunnyvale, CA 94085, (hereinafter called **AOS**), desires to acquire
the entire right, title and interest of said application and invention, and to
any United States and foreign patents to be obtained therefore;

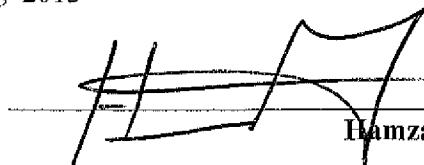
Now therefore for a valuable consideration, receipt whereof is
hereby acknowledged, I, the above named, hereby sell, assign, and transfer
to **AOS**, its successors and assigns, the entire right, title and interest in the
said application and invention therein disclosed for the United States and
foreign countries, and all rights of priority resulting from the filing said
United States application, and I request the Commissioner of Patents to
issue any Letters Patent granted upon the invention set forth in said
application to **AOS** its successors and assigns; and I hereby agree that
AOS may apply for foreign Letters Patent on said invention and I will
execute all papers necessary in connection with the United States and
foreign applications when called upon to do so by

CITY AND

Signed and Sealed at Sunnyvale

DATE

on Jan. 25, 2013


Hamza Yilmaz

ASSIGNMENT

**INVENTOR
AND CITY**

Whereas, I, **MADHUR BOBDE** residing at
Sunnyvale, California, USA

have invented:

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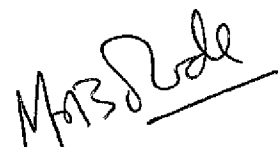
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CITY AND

Signed and Sealed at Sunnyvale, CA

DATE

on Jan 25th, 2013



Madhur Bobde

ASSIGNMENT

**INVENTOR
AND CITY** Whereas, I, **HONG CHANG** residing at
Saratoga, California, USA

have invented:

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foreign applications when called upon to do so by

CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 25th, 2013


Hong Chang

ASSIGNMENT

INVENTOR Whereas, I, YEEHENG LEE residing at
AND CITY San Jose, California, USA

have invented:

TITLE: **DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY
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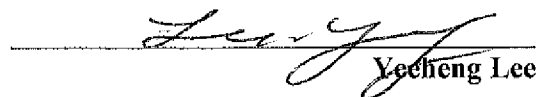
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CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 25th, 2013


Yeeheng Lee

ASSIGNMENT

**INVENTOR
AND CITY** Whereas, I, **DANIEL CALAFUT** residing at
San Jose, California, USA

have invented:

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foreign applications when called upon to do so by

CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 25th, 2013


Daniel Calafut

ASSIGNMENT

INVENTOR
AND CITY

Whereas, I, JONGOH KIM residing at
Portland, Oregon, USA

have invented:

TITLE:

DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY
MOSFETS FOR LOAD SWITCH AND DC-DC APPLICATIONS

DATE INVENTOR
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foreign applications when called upon to do so by

CITY AND

Signed and Sealed at Portland, OR

DATE

on 6/7/2013, 2012


Jongoh Kim

ASSIGNMENT

**INVENTOR
AND CITY** Whereas, I, **SIK LUI** residing at
Sunnyvale, California, USA

have invented:

TITLE: **DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY
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CITY AND Signed and Sealed at Sunnyvale

DATE on Jan. 25, 2013

Sik Lui
Sik Lui

ASSIGNMENT

**INVENTOR
AND CITY** Whereas, I, **JOHN CHEN** residing at
Palo Alto, California, USA

have invented:

TITLE: **DEVICE STRUCTURE AND METHODS OF MAKING HIGH DENSITY
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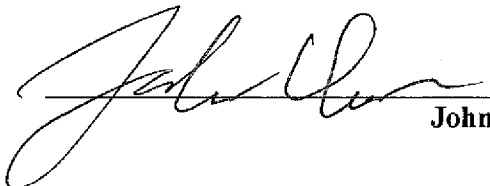
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CITY AND Signed and Sealed at Sunnyvale, CA

DATE on Jan 25th , 2013


John Chen